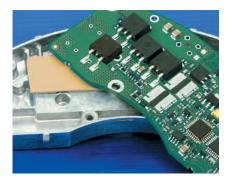
Gap Pad® A3000

Thermally Conductive, Reinforced Gap Filling Material

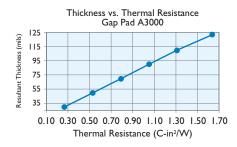
Features and Benefits

- Thermal conductivity: 2.6 W/m-K
- Fiberglass reinforced for puncture, shear and tear resistance
- Reduced tack on one side to aid in application assembly
- · Electrically isolating



Gap Pad A3000 is a thermally conductive, filled-polymer laminate, supplied on a reinforcing mesh for added electrical isolation, easy material handling and enhanced puncture, shear and tear resistance. Gap Pad A3000 has a reinforcement layer on the dark gold side of the material that assists in burn-in and rework processes while the light gold and soft side of the material allows for added compliance.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD A3000					
PROPERTY	IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
Color	Gold	Gold		Visual	
Reinforcement Carrier	Fiberglass	Fiberglass		_	
Thickness (inch) / (mm)	0.015 to 0.125	0.381 to 3.175		ASTM D374	
Inherent Surface Tack (1 side)	I	I		_	
Density (Bulk Rubber) (g/cc)	3.2	3.2		ASTM D792	
Heat Capacity (J/g-K)	1.0	1.0		ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (1)	80	80		ASTM D2240	
Young's Modulus (psi) / (kPa) (2)	50	344		ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200		_	
ELECTRICAL					
Dielectric Breakdown Voltage (Vac)	>5000	>5000		ASTM D149	
Dielectric Constant (1000 Hz)	7.0	7.0		ASTM D150	
Volume Resistivity (Ohm-meter)	1010	1010		ASTM D257	
Flame Rating	V-O	V-O		U.L. 94	
THERMAL					
Thermal Conductivity (W/m-K)	2.6	2.6		ASTM D5470	
THERMAL PERFORMANCE vs. STF	RAIN				
	Deflection (%	6 strain)	10	20	30
Thermal Impedance (°C-in²/W) 0.040" (3)			0.78	0.73	0.68
1) Thirty second delay value Shore 00 hardness scale. 2)Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch ³ . 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial ther-					

Typical Applications Include:

surface roughness, flatness and pressure applied.

- Computer and peripherals
- Heat pipe assemblies
- CDROM / DVD cooling
- Telecommunications
- RDRAM™ memory modules
- Between CPU and heat spreader

Standard Options

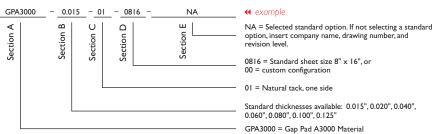
• Area where heat needs to be transferred to a frame, chassis or other type of heat spreader

mal resistance. These values are provided for reference only. Actual application performance is directly related to the

Configurations Available:

• Sheet form, die-cut parts and roll form (converted or unconverted)

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.



www.bergquistcompany.com

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